Features



3.0V/3.3V Adjustable Microprocessor **Supervisory Circuits**

General Description

The MAX793/MAX794/MAX795 microprocessor (µP) supervisory circuits monitor and control the activities of +3.0V/+3.3V µPs by providing backup-battery switchover, among other features such as low-line indication, µP reset, write protection for CMOS RAM, and a watchdog (see the Selector Guide below). The backup-battery voltage can exceed VCC, permitting the use of 3.6V lithium batteries in systems using 3.0V to 3.3V for VCC.

The MAX793/MAX795 offer a choice of reset threshold voltage range (denoted by suffix letter): 3.00V to 3.15V (T), 2.85V to 3.00V (S), and 2.55V to 2.70V (R). The MAX794's reset threshold is set externally with a resistor divider. The MAX793/MAX794 are available in 16-pin DIP and narrow SO packages, and the MAX795 comes in 8-pin DIP and SO packages.

Selector Guide

FEATURE	MAX793	MAX794	MAX795
Active-Low Reset	~	~	✓
Active-High Reset	~	~	
Programmable Reset Threshold		~	
Low-Line Early Warning Output	~	~	
Backup-Battery Switchover	~	~	~
External Switch Driver	~	~	~
Power-Fail Comparator	~	V	
Battery OK Output	V		
Watchdog Input	~	~	
Battery Freshness Seal	~	V	
Manual Reset Input	~	V	
Chip-Enable Gating	~	~	~
Pin-Package	16-DIP/SO	16-DIP/SO	8-DIP/SO

Applications

Battery-Powered Computers and Controllers

Embedded Controllers

Intelligent Controllers

Critical µP Power Monitoring

Portable Equipment

Pin Configurations appear at end of data sheet.

MAX793/MAX794/MAX795

- **♦** Precision Supply-Voltage Monitor: Fixed Reset Trip Voltage (MAX793/MAX795) Adjustable Reset Trip Voltage (MAX794)
- ♦ Guaranteed Reset Assertion to V_{CC} = 1V
- **Backup-Battery Power Switching—Battery** Voltage Can Exceed VCC
- On-Board Gating of Chip-Enable Signals—7ns Max Propagation Delay

MAX793/MAX794 Only

- ♦ Battery Freshness Seal
- **♦** Battery OK Output (MAX793)
- **Uncommitted Voltage Monitor for Power-Fail or Low-Battery Warning**
- ♦ Independent Watchdog Timer (1.6s timeout)
- ♦ Manual Reset Input

Ordering Information

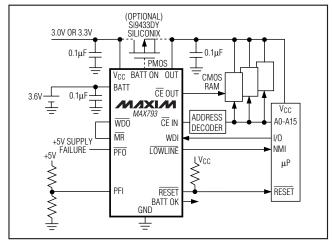
PART*	TEMP RANGE	PIN- PACKAGE
MAX793_CPE	0°C to +70°C	16 Plastic DIP
MAX793_CSE	0°C to +70°C	16 Narrow SO

Ordering Information continued at end of data sheet.

*The MAX793/MAX795 offer a choice of reset threshold voltage. Select the letter corresponding to the desired reset threshold voltage range (T = 3.00V to 3.15V, S = 2.85V to 3.00V, R = 2.85V to 3.00V, R = 3.00V to 3.15V to 3.00V to 3.15V to 3.00V to 3.15V to 3.00V to 3.00V to 3.15V to 3.00V to 3.002.55V to 2.70V) and insert it into the blank to complete the part number. The MAX794's reset threshold is adjustable.

Devices are available in both leaded and lead-free packaging. Specify lead free by adding the + symbol at the end of the part number when ordering.

Typical Operating Circuit



Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

Terminal Voltage (with resp	pect to GND)
	0.3V to +6.0V
	0.3V to +6.0V
All Other Inputs	0.3V to the higher of VCC or VBATT
Continuous Input Current	
Vcc	200mA
VBATT	50mA
GND	20mA
Output Current	
VOUT	200mA
All Other Outputs	20mA

Continuous Power Dissipation ($I_A = +70^{\circ}C$)
8-Pin Plastic DIP (derate 9.09mW/°C above +70°C)727mW
8-Pin SO (derate 5.88mW/°C above +70°C)471mW
16-Pin Plastic DIP (derate 10.53mW/°C above +70°C) .842mW
16-Pin Narrow SO (derate 9.52mW/°C above +70°C)696mW
Operating Temperature Ranges
MAX793_C/MAX794C/MAX795_C 0°C to +70°C
MAX793_E/MAX794E/MAX795_E40°C to +85°C
Storage Temperature Range65°C to +160°C
Lead Temperature (soldering, 10s)+300°C
Soldering Temperature (reflow)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(VCC = 3.17V to 5.5V for the MAX793T/MAX795T, VCC = 3.02V to 5.5V for the MAX793S/MAX795S, VCC = 2.72V to 5.5V for the MAX793R/MAX794/MAX795R, $V_{BATT} = 3.6V$, $V_{BATT} = 3.6V$, V

PARAMETER	SYMBOL	COND	ITIONS	MIN	TYP	MAX	UNITS			
Operating Voltage Range,		MAX79_C	MAX79_C			5.5	V			
V _{CC} , V _{BATT} (Note 1)		MAX79_E		1.1		5.5	5 V			
		MAX793/MAX794,	V _{CC} < 3.6V		46	60				
V _{CC} Supply Current	louppi v	$MR = V_{CC}$	V _{CC} < 5.5V		62	80				
(excluding IOUT, ICE OUT)	ISUPPLY	MAX795	Vcc < 3.6V		35	50	- μΑ			
		IVIAA795	V _{CC} < 5.5V		49	70				
V _{CC} Supply Current in Battery-Backup Mode	ISUPPLY	Vcc = 2.1V,	MAX793/MAX794		32	45	μA			
(excluding I _{OUT})	13011 L1	VBATT = 2.3V	MAX795		24	35	μ, τ			
BATT Supply Current (excluding IOUT) (Note 2)						1	μA			
BATT Leakage Current, Freshness Seal Enabled		V _{CC} = 0V, V _{OUT} = 0V	1			1	μA			
Battery Leakage Current (Note 3)						0.5	μА			
OUT Output Voltage in	Vout	Iout = 75mA		Vcc - 0.3	Vcc - 0.125					
Normal Mode		I _{OUT} = 30mA (Note 4	•	V _{CC} - 0.12	V _{CC} - 0.050		V			
		Iout = 250µA (Note 4	1)	V _{CC} - 0.001	V _{CC} - 0.5mV					
OUT Output Voltage in	Vout	V _{BATT} = 2.3V	I _{OUT} = 250μA	V _{BATT} - 0.1	V _{BATT} - 0.034		V			
Battery-Backup Mode		VBATT = 2.0V	I _{OUT} = 1mA		V _{BATT} - 0.14		, i			
	V _{CC} - V _{BATT}	V _{SW} > V _{CC} > 1.75V (Note 5)		20	65	mV			
Battery Switch Threshold			MAX793T/MAX795T	2.69	2.82	2.95	V			
(V _{CC} falling)	Vsw	V _{BATT} > V _{CC}	MAX793S/MAX795S	2.55	2.68	2.80				
	V 3VV	V 2 V V	V 200	V 3VV	N	(Note 6)	MAX793R/MAX795R/ MAX794	2.30	2.41	2.52
Battery Switch Threshold (VCC rising) (Note 7)	Vcc -	This value is identica VCC rising for VBATT	to the reset threshold, > VRST							
	VBATT	VBATT < VRST			25	65	mV			

ELECTRICAL CHARACTERISTICS (continued)

 $(VCC=3.17V\ to\ 5.5V\ for\ the\ MAX793T/MAX795T,\ VCC=3.02V\ to\ 5.5V\ for\ the\ MAX793S/MAX795S,\ VCC=2.72V\ to\ 5.5V\ for\ the\ MAX793R/MAX795R,\ VBATT=3.6V,\ TA=TMIN\ to\ TMAX,\ unless otherwise\ noted.\ Typical\ values\ are\ at\ TA=+25^{\circ}C.)$

PARAMETER	SYMBOL	COI	NDITIONS	MIN	TYP	MAX	UNITS
TAHAMETER	OTHIBOL	00.	MAX793T/MAX795T	3.00	3.075	3.15	Onic
		V _{CC} falling	MAX793S/MAX795S	2.85	2.925	3.00	
		VCC familing	MAX793R/MAX795R	2.55	2.625	2.70	V
Reset Threshold (Note 8)	VRST		MAX793T/MAX795T	3.00	3.085	3.17	
		V _{CC} rising	MAX793S/MAX795S	2.85	2.935	3.02	
		VCC rising	MAX793R/MAX795R	2.55	2.635	2.72	
RESET IN Threshold		Vcc falling	IVIAA793H/IVIAA793H	1.212	1.240	1.262	
(MAX794 only)	V _{RST} IN	VCC raining VCC rising		1.212	1.250	1.282	V
RESET IN Leakage Current (MAX794 only)		1 00 memig		-25	2	25	nA
Reset Timeout Period	t _{RP}	V _{CC} < 3.6V		140	200	280	ms
LOWLINE-to-Reset Threshold, (VLOWLINE -	VLR	MAX793		30	45	60	mV
V _{RST}), V _{CC} Falling		MAX794		5	15	25	
Low-Line Comparator		MAX793			10		mV
Hysteresis		MAX794			10		mV
		MAX793T/MAX795				3.23	
LOWLINE Threshold,	V _{LL}	MAX793S/MAX795S				3.08	V
V _{CC} Rising		MAX793R/MAX795R				2.78	
		MAX794		1.010	1.040	1.317	
PFI Input Threshold	VTH	V _{PFI} falling V _{PFI} rising		1.212	1.240	1.262	V
PFI Input Current		VPFITISITIS		-25	2	25	nA
PFI Hysteresis, PFI Rising				-23	10	20	mV
BATT OK Threshold (MAX793)	V _{BOK}			2.00	2.25	2.50	V
INPUT AND OUTPUT LEVE	LS						
RESET Output-Voltage High	VoH	ISOURCE = 300μA,	Vcc = V _{RST} min	0.8V _{CC}	0.86V _{CC}		V
BATT OK, BATT ON, WDO, LOWLINE Output-Voltage High	Voh	ISOURCE = 300µA,	V _{CC} = V _{RST} max	0.8V _{CC}	0.86V _{CC}		V
PFO Output-Voltage High	Voн	ISOURCE = 65µA, V	/cc = V _{RST} max	0.8Vcc			V
BATT ON Output- Voltage High	V _{OH}	ISOURCE = 100µA,	V _{CC} = 2.3V, V _{BATT} = 3V	0.8V _{BATT}			V
RESET Output Leakage Current (Note 9)	ILEAK	V _{CC} = V _{RST} max		-1		-1	μΑ
PFO Output Short to GND Current	Isc	V _{CC} = 3.3V, V PFO	= 0V		180	500	μΑ
PFO, RESET, RESET, WDO, LOWLINE Output-Voltage Low	VoL		SET, LOWLINE tested hin; RESET, BATTOK, CC = VRST max		0.08	0.2Vcc	V

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ELECTRICAL CHARACTERISTICS (continued)

(VCC = 3.17V to 5.5V for the MAX793T/MAX795T, VCC = 3.02V to 5.5V for the MAX793S/MAX795S, VCC = 2.72V to 5.5V for the MAX793R/MAX795R, VBATT = 3.6V, TA = TMIN to TMAX, unless otherwise noted. Typical values are at TA = $+25^{\circ}$ C.)

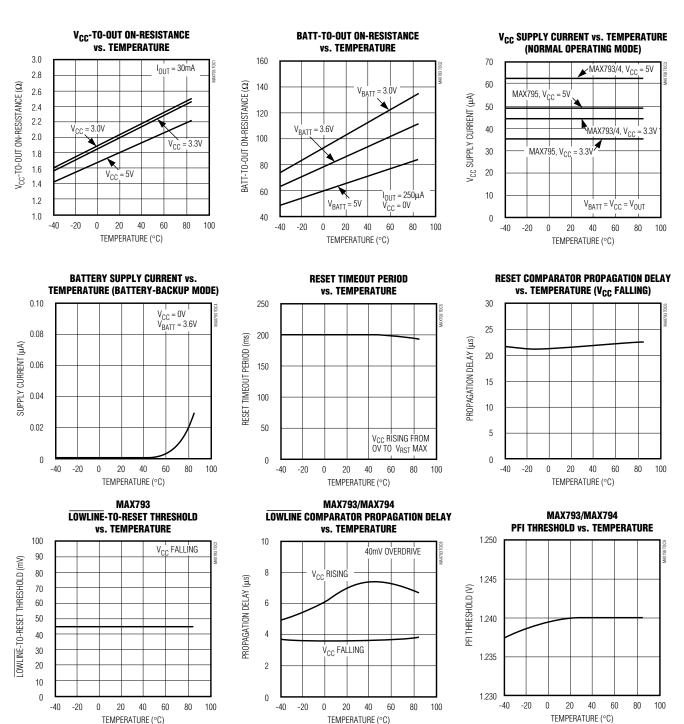
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DECET Output Voltage Lew	\/a.	MAX79_C, $V_{BATT} = V_{CC} = 1.0V$, $I_{SINK} = 40\mu A$		0.13	0.3	V
RESET Output-Voltage Low	VoL	MAX79_E, $V_{BATT} = V_{CC} = 1.2V$, $I_{SINK} = 200\mu A$		0.17	0.3	V
BATT ON Output- Voltage Low	VoL	ISINK = 3.2mA, VCC = VRST max			0.2Vcc	V
All Inputs Including PFO	VIH	V _{RST} max < V _{CC} < 5.5V			0.7V _{CC}	V
(Note 10)	VIL	VRS 111ax < VCC < 3.5V	0.3V _{CC}			V
MANUAL RESET INPUT						
MR Pulse Width	t _{MR}	MAX793/MAX794 only	100			ns
MR-to-Reset Delay	tMD	MAX793/MAX794 only		75	250	ns
MR Pullup Current		MAX793/MAX794 only, $\overline{MR} = 0V$	25	70	250	μΑ
CHIP-ENABLE GATING			•			
CE IN Leakage Current	ILEAK	Disable mode		±10		nA
CE IN-to-CE OUT		Enable mode, VCC = VRST max		46		Ω
Resistance		Lilable Hode, VCC = VRSI IIIax		40		22
CE IN-to-CE OUT Propagation Delay		V _{CC} = V _{RST} max, Figure 9		2	7	ns
CE OUT Drive from CE IN	Voн	VCC = VRST max, IOUT = -1mA, V CE IN = VCC	0.8V _{CC}			V
	V _{OL}	V _{CC} = V _{RST} max, I _{OUT} = 1.6mA, V CE IN = 0V			0.2V _{CC}	V
Reset to CE OUT High Delay				10		μs
CE OUT Output-Voltage High (reset active)	VoH	I _{OH} = 500μA, V _{CC} < 2.3V	0.8V _{BATT}			V
WATCHDOG (MAX793/MAX	(794 only)					
WDI Input Current		0V < V _{CC} < 5.5V	-1	0.01	1	μA
Watchdog Timeout Period	twp		1.00	1.60	2.25	S
WDI Pulse Width			100			ns

- Note 1: V_{CC} supply current, logic-input leakage, watchdog functionality (MAX793/MAX794), MR functionality (MAX793/MAX794), PFI functionality (MAX793/MAX794), and state of RESET and RESET (MAX793/MAX794) tested at V_{BATT} = 3.6V and V_{CC} = 5.5V. The state of RESET is tested at V_{CC} = V_{CC} min.
- Note 2: Tested at V_{BATT} = 3.6V, V_{CC} = 3.5V and 0V. The battery current rises to 10μA over a narrow transition window around V_{CC} = 1.9V.
- Note 3: Leakage current into the battery is tested under the worst-case conditions at V_{CC} = 5.5V, V_{BATT} = 1.8V and V_{CC} = 1.5V, V_{BATT} = 1.0V.
- **Note 4:** Guaranteed by design.
- Note 5: When Vsw > Vcc > VBATT, OUT remains connected to Vcc until Vcc drops below VBATT. The Vcc-to-VBATT comparator has a small 15mV typical hysteresis to prevent oscillation. For Vcc < 1.75V (typical), OUT switches to BATT regardless of VBATT.
- Note 6: When V_{BATT} > V_{CC} > V_{SW}, OUT remains connected to V_{CC} until V_{CC} drops below the battery switch threshold (V_{SW}).
- Note 7: OUT switches from BATT to V_{CC} when V_{CC} rises above the reset threshold, if V_{BATT} > V_{RST}. In this case, switchover back to V_{CC} occurs at the exact voltage that causes reset to be asserted, however, switchover occurs 200ms prior to reset. If V_{BATT} < V_{RST}, OUT switches from BATT to V_{CC} when V_{CC} exceeds V_{BATT}.
- Note 8: The reset threshold tolerance is wider for V_{CC} rising than for V_{CC} falling to accommodate the 10mV typical hysteresis, which prevents internal oscillation.
- Note 9: The leakage current into or out of the RESET pin is tested with RESET not asserted (RESET output high impedance).
- Note 10: PFO is normally an output, but is used as an input when activating the battery freshness seal.

· ______/V|/X|/V|

Typical Operating Characteristics

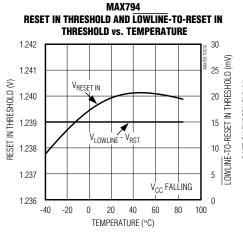
 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$

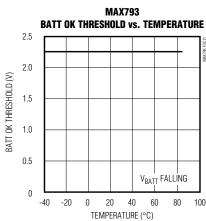


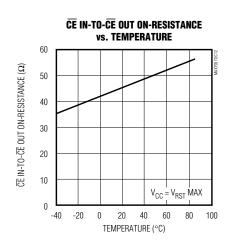
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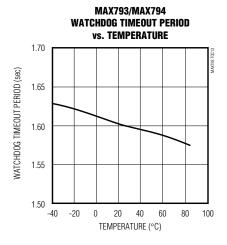
_Typical Operating Characteristics (continued)

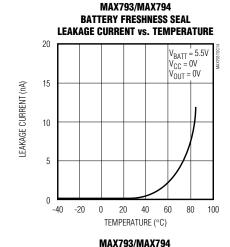
 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$

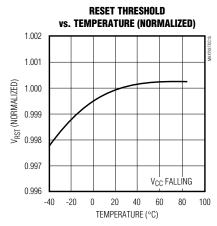


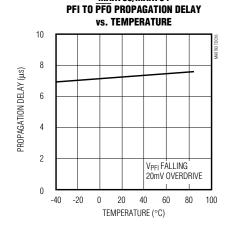












Pin Description

Р	IN			
MAX793/ MAX794	MAX795	NAME	FUNCTION	
1	1	OUT	Supply Output for CMOS RAM. When V _{CC} rises above the reset threshold or above V _{BATT} , OUT is connected to V _{CC} through an internal p-channel MOSFET switch. When V _{CC} falls below V _{SW} and V _{BATT} , BATT connects to OUT.	
2	2	Vcc	Main Supply Input	
3		BATT OK (MAX793)	Battery Status Output. High in normal operating mode when VBATT exceeds VBOK, otherwise low. VBATT is checked continuously. Disabled and logic low while VCC is below VSW.	
3	_	RESET IN (MAX794)	Reset Input. Connect to an external resistor-divider to select the reset threshold. The reset threshold can be programmed anywhere in the Vsw to 5.5V range.	
4	_	PFI	Power-Fail Comparator Input. When PFI is less than V _{PFT} or when V _{CC} falls below V _{SW} , PFO goes low; otherwise, PFO remains high (see <i>Power-Fail Comparator</i> section). Connect to V _{CC} if unused.	
5	3	BATT ON	Logic Output/External Bypass Switch-Driver Output. High when OUT switches to BATT. Low when OUT switches to V _{CC} . Connect the base/gate of PNP/PMOS transistor to BATT ON for I _{OUT} requirements exceeding 75mA.	
6	4	GND	Ground	
7	_	PFO	Power-Fail Comparator Output. When PFI is less than V _{PFT} or when V _{CC} falls below V _{SW} , PFO goes low; otherwise, PFO remains high. PFO is also used to enable the battery freshness seal (see <i>Battery Freshness Seal</i> and <i>Power-Fail Comparator</i> sections).	
8	_	MR	Manual Reset Input. A logic low on MR asserts reset. Reset remains asserted as long as MR is low and for 200ms after MR returns high. The active-low input has an internal 70μA pullup current. It can be driven from a TTL- or CMOS-logic line or shorted to ground with a switch. Leave open if unused.	
9	_	WDO	Watchdog Output. WDO goes low if WDI remains either high or low for longer than the watchdog timeout period. WDO returns high on the next transition of WDI. WDO is a logic high for V _{SW} < V _{CC} < V _{RST} , and low when V _{CC} is below V _{SW} .	
10	_	WDI	Watchdog Input. If WDI remains either high or low for longer than the watchdog timeout period, the internal watchdog timer runs out and WDO goes low. WDO returns high on the next transition of WDI. Connect WDO to MR to generate a reset due to a watchdog fault.	
11	5	CE IN	Chip-Enable Input. The input to the chip-enable gating circuit. Connect to GND if unused.	
12	6	CE OUT	Chip-Enable Output. \overline{CE} OUT goes low only when \overline{CE} IN is low and reset is not asserted. If \overline{CE} IN is low when reset is asserted, \overline{CE} OUT remains low for 10 μ s or until \overline{CE} IN goes high, whichever occurs first. \overline{CE} OUT is pulled up to OUT.	
13	_	RESET	Active-High Reset Output. Sources and sinks current. RESET is the inverse of RESET.	
14	_	LOWLINE	Early Power-Fail Warning Output. Low when V _{CC} falls to V _{LR} . This output can be used to generate an NMI to provide early warning of imminent power failure.	
15	7	RESET	Open-Drain, Active-Low Reset Output. Pulses low for 200ms when triggered, and stays low whenever V _{CC} is below the reset threshold or when $\overline{\text{MR}}$ is a logic low. It remains low for 200ms after either V _{CC} rises above the reset threshold, the watchdog triggers a reset ($\overline{\text{WDO}}$ connected to $\overline{\text{MR}}$), or $\overline{\text{MR}}$ goes low to high.	
16	8	BATT	Backup-Battery Input. When V_{CC} falls below V_{SW} and V_{BATT} , OUT switches from V_{CC} to BATT. When V_{CC} rises above the reset threshold or above V_{BATT} , OUT reconnects to V_{CC} . V_{BATT} can exceed V_{CC} . Connect V_{CC} , OUT, and BATT together if no battery is used.	

MIXIM -

Detailed Description

General Timing Characteristics

The MAX793/MAX794/MAX795 are designed for 3.3V and 3V systems, and provide a number of supervisory functions (see the *Selector Guide* on the front page). Figures 1 and 2 show the typical timing relationships of the various outputs during power-up and power-down with typical VCC rise and fall times.

Manual Reset Input (MAX793/MAX794)

Many microprocessor-based products require manual-reset capability, allowing the operator, a test technician, or external logic circuitry to initiate a reset. On the MAX793/MAX794, a logic low on $\overline{\text{MR}}$ asserts reset. Reset remains asserted while $\overline{\text{MR}}$ is low, and for t_{RP} (200ms) after it returns high. During the first half of the reset time-

out period (tRP), the state of $\overline{\text{MR}}$ is ignored if $\overline{\text{PFO}}$ is externally forced low to facilitate enabling the battery freshness seal. $\overline{\text{MR}}$ has an internal 70µA pullup current, so it can be left open if it is not used. This input can be driven with TTL- or CMOS-logic levels, or with open-drain/collector outputs. Connect a normally open momentary switch from $\overline{\text{MR}}$ to GND to create a manual-reset function; external debounce circuitry is not required. If $\overline{\text{MR}}$ is driven from long cables or the device is used in a noisy environment, connect a 0.1µF capacitor from $\overline{\text{MR}}$ to ground to provide additional noise immunity.

Reset Outputs

A microprocessor's (μ P's) reset input starts the μ P in a known state. These MAX793/MAX794/MAX795 μ P supervisory circuits assert a reset to prevent code execution errors during power-up, power-down, and

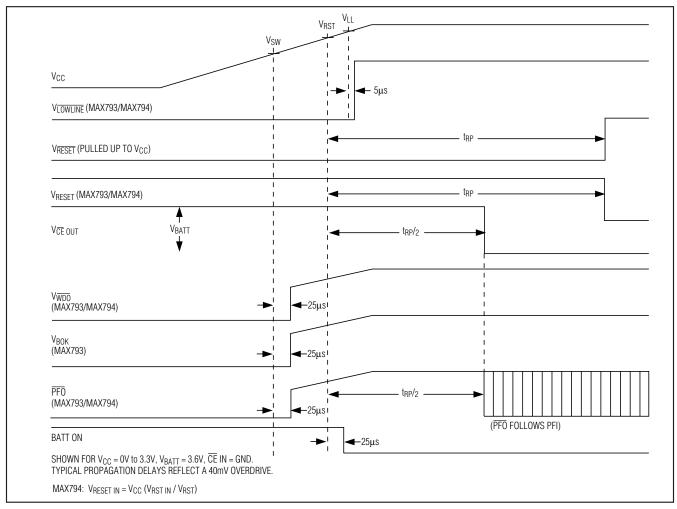


Figure 1. Timing Diagram, VCC Rising

brownout conditions. RESET is guaranteed to be a logic low for 0V < V_{CC} < V_{RST}, provided V_{BATT} is greater than 1V. Without a backup battery (V_{BATT} = V_{CC} = V_{OUT}), RESET is guaranteed valid for V_{CC} \geq 1V. Once V_{CC} exceeds the reset threshold, an internal timer keeps RESET low for the reset timeout period (t_{RP}); after this interval, RESET becomes high impedance (Figure 2). RESET is an open-drain output, and requires a pullup resistor to V_{CC} (Figure 3). Use a 4.7k Ω to 1M Ω pullup resistor that provides sufficient current to assure the proper logic levels to the μP .

If a brownout condition occurs (VCC dips below the reset threshold), $\overline{\text{RESET}}$ goes low. Each time $\overline{\text{RESET}}$ is asserted, it stays low for the reset timeout period. Any time VCC goes below the reset threshold, the internal timer restarts.

The watchdog output (WDO) can also be used to initiate a reset. See the *Watchdog Output* section.

The RESET output is the inverse of the RESET output, and it can both source and sink current.

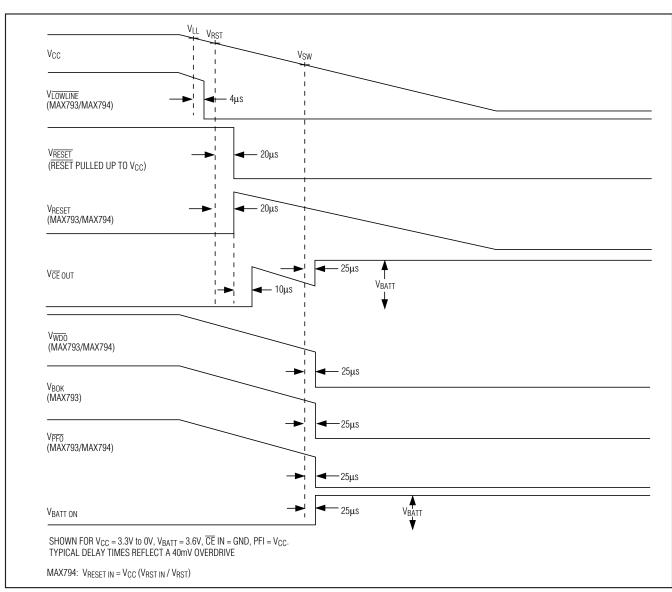


Figure 2. Timing Diagram, VCC Falling

MIXIM

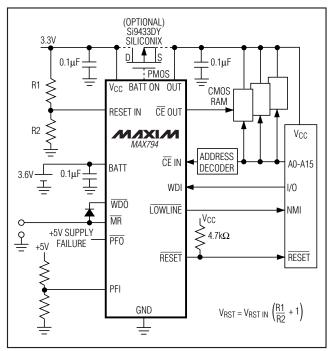


Figure 3. MAX794 Standard Application Circuit

Reset Threshold

The MAX793T/MAX795T are intended for 3.3V systems with a $\pm 5\%$ power-supply tolerance and a 10% systems tolerance. Except when $\overline{\text{MR}}$ is asserted, reset does not assert as long as the power supply remains above 3.15V (3.3V - 5%). Reset is guaranteed to assert before the power supply falls below 3.0V (3.3V - 10%).

The MAX793S/MAX795S are designed for $3.3V \pm 10\%$ power supplies. Except when \overline{MR} is asserted, they are guaranteed not to assert reset as long as the supply remains above 3.0V (3.0V is just above 3.3V - 10%). Reset is guaranteed to assert before the power supply falls below 2.85V (3.3V - 14%).

The MAX793R/MAX795R are optimized to monitor 3.0V $\pm 10\%$ power supplies. Reset does not occur until V_{CC} falls below 2.7V (3.0V - 10%), but is guaranteed to occur before the supply falls below 2.55V (3.0V - 15%).

Program the MAX794's reset threshold with an external voltage divider to RESET IN. The reset-threshold tolerance is a combination of the RESET IN tolerance and the tolerance of the resistors used to make the external voltage divider. Calculate the reset threshold as follows:

$$V_{RST} = V_{RST} IN (R1/R2 + 1)$$

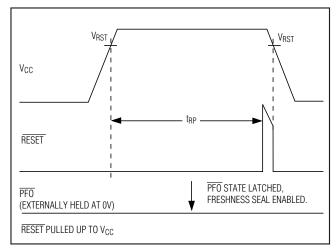


Figure 4. Battery Freshness Seal Enable Timing

Using the standard application circuit (Figure 3), the reset threshold can be programmed anywhere in the range of Vsw (the battery switch threshold) to 5.5V. Reset is asserted when Vcc falls below Vsw.

Battery Freshness Seal

The MAX793/MAX794's battery freshness seal disconnects the backup battery from internal circuitry until it is needed. This allows an OEM to ensure that the backup battery connected to BATT is fresh when the final product is put to use. To enable the freshness seal, connect a battery to BATT, ground PFO, bring VCC above the reset threshold, and hold it there until reset is deasserted following the reset timeout period, then bring VCC back down again (Figure 4). Once the battery freshness seal is enabled (disconnecting the backup battery from the internal circuitry and anything connected to OUT), it remains enabled until VCC is brought above VRST. Note that connecting PFO to MR does not interfere with battery freshness seal operation.

BATT OK Output (MAX793)

BATT OK indicates the status of the backup battery. When reset is not asserted, the MAX793 checks the battery voltage continuously. If VBATT is below VBOK (2.0V min), BATT OK goes low; otherwise, it remains pulled up to VCC. BATT OK also goes low when VCC goes below VSW.

Watchdog Input (MAX793/MAX794)

In the MAX793/MAX794, the watchdog circuit monitors the μ P's activity. If the μ P does not toggle the watchdog input (WDI) within 1.6s, $\overline{\text{WDO}}$ goes low. The internal 1.6s timer is cleared and $\overline{\text{WDO}}$ returns high either when

10 _______/V|/X|/V|

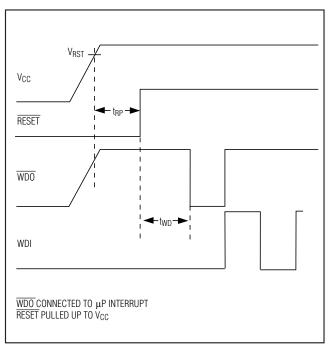


Figure 5. Watchdog Timing Relationship

a reset occurs or when a transition (low-to-high or high-to-low) takes place at WDI. As long as reset is asserted, the timer remains cleared and does not count. As soon as reset is released or WDI changes state, the timer starts counting (Figure 5). WDI can detect pulses as short as 100ns. Unlike the 5V MAX690 family, the watchdog function **cannot** be disabled.

Watchdog Output (MAX793/MAX794)

In the MAX793/MAX794, $\overline{\text{WDO}}$ remains high ($\overline{\text{WDO}}$ is pulled up to VCC) if there is a transition or pulse at WDI during the watchdog timeout period. $\overline{\text{WDO}}$ goes low if no transition occurs at WDI during the watchdog timeout period. The watchdog function is disabled and $\overline{\text{WDO}}$ is a logic high when reset is asserted if VCC is above Vsw. $\overline{\text{WDO}}$ is a logic low when VCC is below Vsw.

If a system reset is desired on every watchdog fault, simply diode-OR connect \overline{WDO} to \overline{MR} (Figure 6). When a watchdog fault occurs in this mode, \overline{WDO} goes low, pulling \overline{MR} low, which causes a reset pulse to be issued. Ten microseconds after reset is asserted, the watchdog timer clears and \overline{WDO} returns high. This delay results in a 10µs pulse at \overline{WDO} , allowing external circuitry to capture a watchdog fault indication. A continuous high or low on WDI causes 200ms reset pulses to be issued every 1.6s.

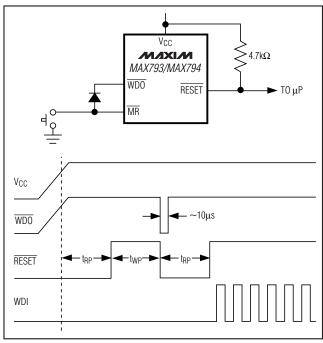


Figure 6. Generating a Reset on Each Watchdog Fault

Chip-Enable Signal Gating

Internal gating of chip-enable (CE) signals prevents erroneous data from corrupting CMOS RAM in the event of an undervoltage condition. The MAX793/MAX794/MAX795 use a series transmission gate from \overline{CE} IN to \overline{CE} OUT During normal operation (reset not asserted), the CE transmission gate is enabled and passes all CE transitions. When reset is asserted, this path becomes disabled, preventing erroneous data from corrupting the CMOS RAM. The short CE propagation delay from \overline{CE} IN to \overline{CE} OUT enables these μP supervisors to be used with most μPs . If \overline{CE} IN is low when reset asserts, \overline{CE} OUT remains low for typically 10 μ s to permit completion of the current write cycle.

Chip-Enable Input

The CE transmission gate is disabled and $\overline{\text{CE}}$ IN is high impedance (disabled mode) while reset is asserted. During a power-down sequence when V_{CC} passes the reset threshold, the CE transmission gate disables and $\overline{\text{CE}}$ IN immediately becomes high impedance if the voltage at $\overline{\text{CE}}$ IN is high. If $\overline{\text{CE}}$ IN is low when reset asserts, the CE transmission gate disables at the moment $\overline{\text{CE}}$ IN goes high, or 10µs after reset asserts, whichever occurs first (Figure 8). This permits the current write cycle to complete during power-down.

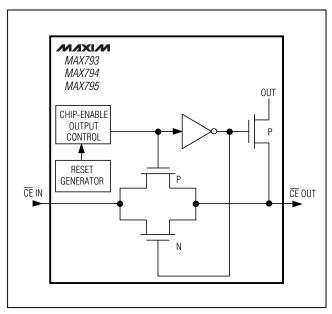


Figure 7. Chip-Enable Transmission Gate

The CE transmission gate remains disabled and $\overline{\text{CE}}$ IN remains high impedance (regardless of $\overline{\text{CE}}$ IN activity) for the first half of the reset timeout period (the / 2), any time a reset is generated. While disabled, $\overline{\text{CE}}$ IN is high impedance. When the CE transmission gate is enabled, the impedance of $\overline{\text{CE}}$ IN appears as a 46Ω resistor in series with the load at $\overline{\text{CE}}$ OUT.

The propagation delay through the CE transmission gate depends on $\underline{V_{CC}}$, the source impedance of the drive connected to \overline{CE} IN, and the loading on \overline{CE} OUT. The CE propagation delay is production tested from the 50% point on \overline{CE} IN to the 50% point on \overline{CE} OUT using a 50 Ω driver and 50pF of load capacitance (Figure 9). For minimum propagation delay, minimize the capacitive load at \overline{CE} OUT and use a low-output-impedance driver.

Chip-Enable Output

When the CE transmission gate is enabled, the impedance of $\overline{\text{CE}}$ OUT is equivalent to a 46 Ω resistor in series with the source driving $\overline{\text{CE}}$ IN. In the disabled mode, the transmission gate is off and an active pullup connects $\overline{\text{CE}}$ OUT to OUT (Figure 8). This pullup turns off when the transmission gate is enabled.

Early Power-Fail Warning (MAX793/MAX794)

Critical systems often require an early warning indicating that power is failing. This warning provides time for the μP to store vital data and take care of any additional "housekeeping" functions, before the power supply gets too far out of tolerance for the μP to operate reliably. The MAX793/MAX794 offer two methods of achieving this early warning. If access to the unregulated supply is feasible, the power-fail comparator input (PFI) can be connected to the unregulated supply through a voltage divider, with the power-fail comparator output (PFO) providing the NMI to the μP (Figure

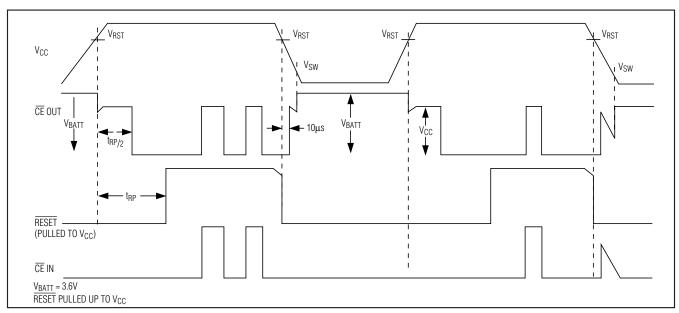


Figure 8. Chip-Enable Timing

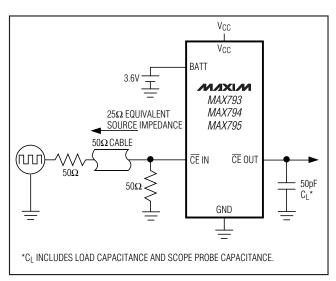


Figure 9. CE Propagation Delay Test Circuit

10). If there is no easy access to the unregulated supply, the $\overline{\text{LOWLINE}}$ output can be used to generate an NMI to the μP (see $\overline{\text{LOWLINE}}$ Output section).

LOWLINE Output (MAX793/MAX794)

The low-line comparator monitors V_{CC} with a threshold voltage typically 45mV above the reset threshold (10mV of hysteresis) for the MAX793, and 15mV above RESET IN (4mV of hysteresis) for the MAX794. For normal operation (V_{CC} above the reset threshold), $\overline{\text{LOWLINE}}$ is pulled to V_{CC}. Use $\overline{\text{LOWLINE}}$ to provide an NMI to the μP when power begins to fall.

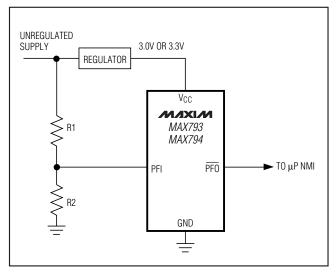


Figure 10. Using the Power-Fail Comparator to Generate Power-Fail Warning

In most battery-operated portable systems, reserve energy in the battery provides ample time to complete the shutdown routine once the low-line warning is encountered and before reset asserts. If the system must also contend with a more rapid V_{CC} fall time, such as when the main battery is disconnected or a high-side switch is opened during normal operation, use capacitance on the V_{CC} line to provide time to execute the shutdown routine (Figure 11).

First, calculate the worst-case time required for the system to perform its shutdown routine. Then, with the worst-case shutdown time, the worst-case load current, and the minimum low-line to reset threshold (V_{LR} min), calculate the amount of capacitance required to allow the shutdown routine to complete before reset is asserted:

CHOLD > ILOAD x tSHDN / VLR

where I_{LOAD} is the current being drained from the capacitor, V_{LR} is the low-line to reset threshold difference (V_{LL} - V_{RST}), and t_{SHDN} is the time required for the system to complete an orderly shutdown routine.

Power-Fail Comparator (MAX793/MAX794)

The MAX793/MAX794's PFI input is compared to an internal reference. If PFI is less than the power-fail threshold (VPFT), PFO goes low. The power-fail comparator is intended for use as an undervoltage detector to signal a failing power supply (Figure 12). However, the comparator does not need to be dedicated to this function because it is completely separate from the rest of the circuitry.

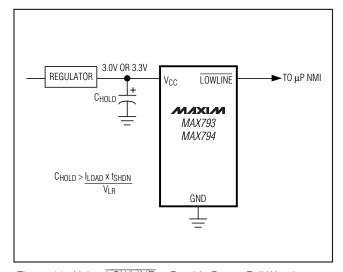


Figure 11. Using $\overline{\text{LOWLINE}}$ to Provide Power-Fail Warning to the μP

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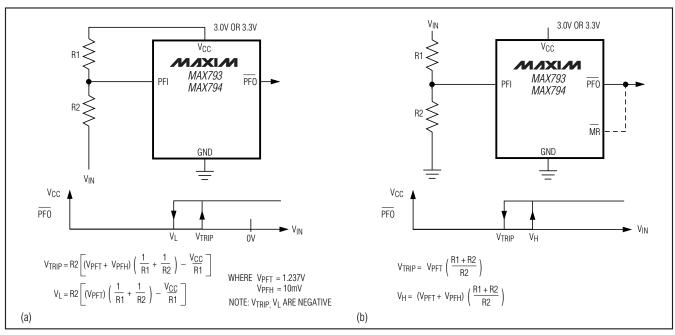


Figure 12. Using the Power-Fail Comparator to Monitor an Additional Power Supply: (a) VIN Is Negative, (b) VIN Is Positive

The power-fail comparator turns off and \overline{PFO} goes low when VCC falls below Vsw on power-down. During the first half of the reset timeout period (tRP), \overline{PFO} is forced high, irrespective of VPFI. At the beginning of the second half of tRP, the power-fail comparator is enabled and \overline{PFO} follows PFI. If the comparator is unused, connect PFI to VCC and leave \overline{PFO} unconnected. \overline{PFO} can be connected to MR so that a low voltage on PFI generates a reset (Figure 12b). In this configuration, when the monitored voltage causes PFI to fall below VPFT, \overline{PFO} pulls \overline{MR} low, causing a reset to be asserted. Reset remains asserted as long as \overline{PFO} holds \overline{MR} low, and for 200ms after \overline{PFO} pulls \overline{MR} high when the monitored supply is above the programmed threshold.

Backup-Battery Switchover

In the event of a brownout or power failure, it may be necessary to preserve the contents of RAM. With a backup battery installed at BATT, the devices automatically switch RAM to backup power when VCC falls. In order to allow the backup battery (e.g., a 3.6V lithium cell) to have a higher voltage than VCC, this family of μP supervisors (designed for 3.3V and 3V systems) does not always connect BATT to OUT when VBATT is greater than VCC. BATT connects to OUT (through a 140 Ω switch) either when VCC falls below VsW and

VBATT is greater than VCC, **or** when VCC falls below 1.75V (typ) regardless of the BATT voltage.

Switchover at VSW ensures that battery-backup mode is entered before VOUT gets too close to the 2.0V minimum required to reliably retain data in most CMOS RAM, (switchover at higher VCC voltages would decrease backup-battery life). When VCC recovers, switchover is deferred either until VCC crosses VBATT if VBATT is below VRST, or when VCC rises above the reset threshold (VRST) if VBATT is above VRST. This power-up switchover technique prevents VCC from charging the backup battery through OUT when using an external transistor driven by BATT ON. OUT connects to VCC through a 4Ω (max) PMOS power switch when VCC crosses the reset threshold (Figure 13).

BATT ON (MAX793/MAX794)

BATT ON is high when OUT is connected to BATT. Although BATT ON can be used as a logic output to indicate the battery switchover status, it is most often used as a gate or base drive for an external pass transistor for high-current applications (see *Driving an External Switch with BATT ON* in the *Applications Information* section). When VCC exceeds VRST on power-up, BATT ON sinks 3.2mA at 0.4V. In battery-backup mode, this terminal sources 100µA from BATT.

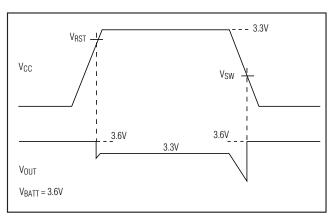


Figure 13. Battery Switchover Timing

Table 1. Input and Output Status in Battery-Backup Mode

	,					
PIN NAME	STATUS					
OUT	Connected to BATT through an internal 140Ω switch					
Vcc	Disconnected from OUT					
BATT ON	Pulled up to BATT					
BATT OK	Logic low					
PFI	Disabled					
PFO	Logic low					
MR	Disabled, but still pulled up to V _{CC}					
WDO	Logic low					
WDI	Disabled					
RESET	Logic low					
RESET	Pulled up to V _{CC}					
BATT	Connected to OUT					
LOWLINE	Logic low					
<u>CE</u> IN	High impedance					
CE OUT	Pulled to BATT					

_Applications Information

These µP supervisory circuits are not short-circuit protected. Shorting V_{OUT} to ground, excluding power-up transients such as charging a decoupling capacitor, destroys the device. Decouple both V_{CC} and BATT pins to ground by placing 0.1µF ceramic capacitors as close to the device as possible.

Driving an External Switch with BATT ON

BATT ON can be directly connected to the base of a PNP transistor or the gate of a PMOS transistor. The PNP connection is straightforward: connect the emitter

to V_{CC}, the collector to OUT, and the base to BATT ON (Figure 14a). No current-limiting resistor is required, but a resistor connecting the base of the PNP to BATT ON can be used to limit the current drawn from V_{CC}, prolonging battery life in portable equipment.

If you are using a PMOS transistor, however, it must be connected backwards from the traditional method. Connect the gate to BATT ON, the drain to VCC, and the source to OUT (Figure 14b). This method orients the body diode from VCC to OUT and prevents the backup battery from discharging through the FET when its gate is high. Two PMOS transistors in the Siliconix LITTLE FOOT® series are specified with VGS down to -2.7V. The Si9433DY has a maximum $100m\Omega$ drain-source on-resistance with 2.7V of gate drive and a 2A drain-source on-resistance with 2.7V of gate drive and a 5.1A drain-source current.

Using a Super Cap as a Backup Power Source

Super caps are capacitors with extremely high capacitance values (e.g., order of 0.47F) for their size. Figure 15 shows two ways to use a super cap as a backup power source. The super cap can be connected through a diode to the 3V input (Figure 15a); or, if a 5V supply is also available, the super cap can be charged up to the 5V supply (Figure 15b), allowing a longer backup period. Since VBATT can exceed VCC while VCC is above the reset threshold, there are no special precautions when using these μP supervisors with a super cap.

Operation without a Backup Power Source

These μP supervisors were designed for battery-backed applications. If a backup battery is not used, connect BATT, OUT, and VCC together, or use a different μP supervisor.

Replacing the Backup Battery

The backup power source can be removed while VCC remains valid, without danger of triggering a reset pulse, provided that BATT is decoupled with a $0.1\mu F$ capacitor to ground. As long as VCC stays above the reset threshold, battery-backup mode cannot be entered.

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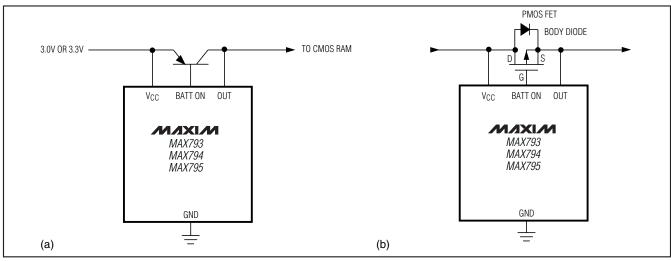


Figure 14. Driving an External Transistor with BATT ON

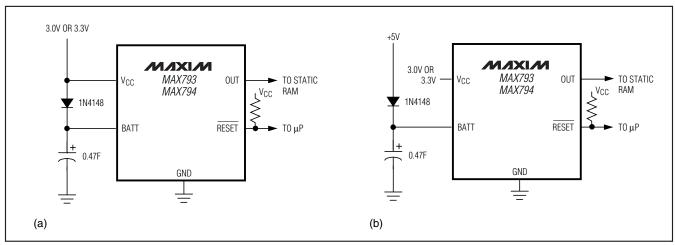


Figure 15. Using a Super Cap as a Backup Source

Adding Hysteresis to the Power-Fail Comparator (MAX793/MAX794)

The power-fail comparator has a typical input hysteresis of 10mV. This is sufficient for most applications where a power-supply line is being monitored through an external voltage divider (see the section *Monitoring an Additional Power Supply*).

If additional noise margin is desired, connect a resistor between PFO and PFI as shown in Figure 16a. Select the ratio of R1 and R2 such that PFI sees V_{PFT} when V_{IN} falls to its trip point (V_{TRIP}). R3 adds the additional hysteresis and should typically be more than 10 times the value of R1 or R2. The hysteresis window extends

both above (V_H) and below (V_L) the original trip point (V_{TRIP}).

Connecting an ordinary signal diode in series with R3, as shown in Figure 16b, causes the lower trip point (VL) to coincide with the trip point without hysteresis (VTRIP), so the entire hysteresis window occurs above VTRIP. This method provides additional noise margin without compromising the accuracy of the power-fail threshold when the monitored voltage is falling. It is useful for accurately detecting when a voltage falls past a threshold. The current through R1 and R2 should be at least $1\mu A$ to ensure that the 25nA (max over temperature) PFI input current does not shift the trip point. R3 should be larger than $82k\Omega$ so it does not load down the \overline{PFO} pin. Capacitor C1 is optional, and adds noise rejection.

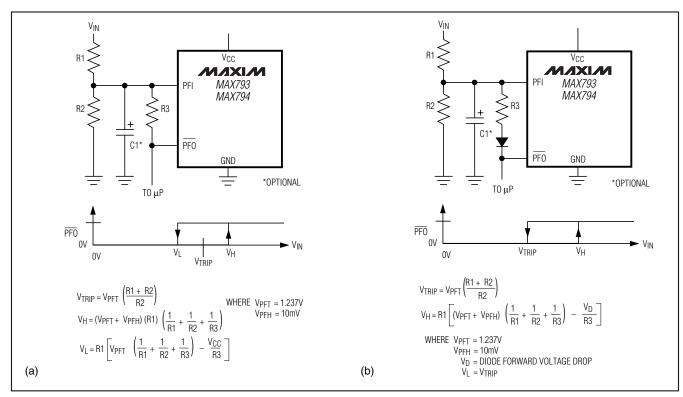


Figure 16. Adding Hysteresis to the Power-Fail Comparator: (a) Symmetrical Hysteresis, (b) Hysteresis Only on Rising VIN

Monitoring an Additional Power Supply

These μP supervisors can monitor either positive or negative supplies using a resistor voltage divider to PFI. PFO can be used to generate an interrupt to the μP or to cause reset to assert (Figure 12).

Interfacing to µPs with Bidirectional Reset Pins

Since the \overline{RESET} output is open drain, the MAX793/MAX794/MAX795 interface easily with μPs that have bidirectional reset pins, such as the Motorola 68HC11. Connecting the \overline{RESET} output of the μP supervisor directly to the \overline{RESET} input of the microcontroller with a single pullup resistor allows either device to assert reset (Figure 17).

Negative-Going Vcc Transients

These supervisors are relatively immune to short-duration negative-going VCC transients (glitches) while issuing resets to the μP during power-up, power-down, and brownout conditions. Therefore, resetting the μP when VCC experiences only small glitches is usually not recommended.

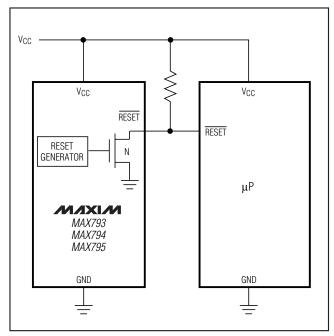


Figure 17. Interfacing to μPs with Bidirectional Reset I/O

Figure 18 shows maximum transient duration vs. reset-comparator overdrive, for which reset pulses are **not** generated. The graph was produced using negative-going VCC pulses, starting at 3.3V and ending below the reset threshold by the magnitude indicated (reset comparator overdrive). The graph shows the maximum pulse width a negative-going VCC transient can typically have without causing a reset pulse to be issued. As the amplitude of the transient increases (i.e., goes farther below the reset threshold), the maximum allowable pulse width decreases. Typically, a VCC transient that goes 40mV below the reset threshold and lasts for 10µs or less does not cause a reset pulse to be issued.

A 0.1µF bypass capacitor mounted close to the V_{CC} pin provides additional transient immunity.

Watchdog Software Considerations

There is a way to help the watchdog timer monitor software execution more closely, which involves setting and resetting the watchdog input at different points in the program rather than pulsing the watchdog input high-low-high or low-high-low. This technique avoids a stuck loop, in which the watchdog timer would continue to be reset within the loop, keeping the watchdog from timing out. Figure 19 shows an example of a flow diagram where the I/O driving the watchdog input is set high at the beginning of the program, set low at the beginning of every subroutine or loop, then set high again when the program returns to the beginning. If the program should hang in any subroutine, the problem would quickly be corrected, since the I/O is continually set low and the watchdog timer is allowed to time out, causing a reset or interrupt to be issued.

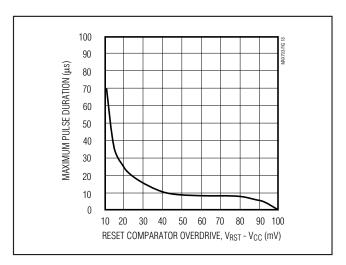


Figure 18. Maximum Transient Duration without Causing a Reset Pulse vs. Reset Comparator Overdrive

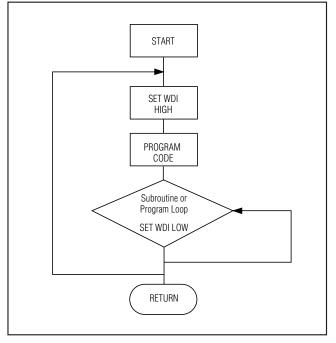


Figure 19. Watchdog Flow Diagram

_Ordering Information (continued)

PART*	TEMP RANGE	PIN- PACKAGE
MAX793_EPE	-40°C to +85°C	16 Plastic DIP
MAX793_ESE	-40°C to +85°C	16 Narrow SO
MAX794CPE	0°C to +70°C	16 Plastic DIP
MAX794CSE	0°C to +70°C	16 Narrow SO
MAX794EPE	-40°C to +85°C	16 Plastic DIP
MAX794ESE	-40°C to +85°C	16 Narrow SO
MAX795_CPA	0°C to +70°C	8 Plastic DIP
MAX795_CSA	0°C to +70°C	8 SO
MAX795_EPA	-40°C to +85°C	8 Plastic DIP
MAX795_ESA	-40°C to +85°C	8 SO

^{*}The MAX793/MAX795 offer a choice of reset threshold voltage. Select the letter corresponding to the desired reset threshold voltage range (T = 3.00V to 3.15V, S = 2.85V to 3.00V, R = 2.55V to 2.70V) and insert it into the blank to complete the part number. The MAX794's reset threshold is adjustable.

Devices are available in both leaded and lead-free packaging. Specify lead free by adding the + symbol at the end of the part number when ordering.

Chip Information

TRANSISTOR COUNT: 1271

TOP VIEW 16 BATT RESET 15 V_{CC} (RESET IN) BATT OK 14 LOWLINE 13 RESET MAX793 **MAX794** BATT ON 12 CE OUT 11 CE IN GND PF0 10 WDI 9 WD0 MR **DIP/Narrow SO** OUT 8 BATT $V_{\rm CC}$ 7 RESET MAX795 BATT ON 3 6 CE OUT 5 CE IN GND

Pin Configurations

Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

DIP/SO

() ARE FOR MAX794

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
8 SO	S8-2	21-0041
8 Plastic Dip	R8-1	21-0043
16 Plastic Dip	P16-1	21-0043
16 Narrow SO	S16-1	<u>21-0041</u>

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	2/95	Initial release	
5	2/07	Revised Electrical Characteristics.	4
6	3/10	Revised Absolute Maximum Ratings and Chip-Enable Input section.	1, 2

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